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A method of forming a conductor wiring pattern,
                                                                                                         forming a first insulating layer on a
                        torming a rirst insulating a second,

torming a rirst insulating a second,

surface of a substrate and also forming a second,

surface of a substrate and rock, and recommendations are recommendations.
              comprising the following steps of:
                                                                                                                          light-exposing and developing the second
                              surrace or a substrate and also rorming a second thereon;
photosensitive insulating resin agent and also rorming a second thereon;
                                          insulating layer to form pattern grooves so that the
                                                Insulating layer to form pattern grooves so that the exposed at bottoms of the first insulating.
                                                                                                                                                  forming a plating seed layer on the second
                                                                forming a plating seed layer on the pattern forming a plating inner surfaces of the nlating layer including inner surfaces on the nlating layer increased and then forming a resist nattern on the nlating layer forming a resist nattern on the nlating layer increased and then forming a resist nattern on the nlating layer including a resist nattern on the nlating layer including a resist nattern on the nlating layer including a resist nattern on the pattern on the pattern on the pattern on the pattern on the nlating layer including inner surfaces.
                                                                       insulating layer including a resist pattern on the plating a resist pattern on arrower.

grooves and then for nortions of the nattern arrowers.
                                                                            grooves and then for portions of the pattern arrows with a seed layer except filling the pattern arrows with a
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                                                                                       conductor by an electroniv laver. and conductor by an electroniv laver.
                                                       Pattern grooves;
                                                                                                         removing the seed layer to form wiring rattern and also the surface of the seed layer to form wiring the seed l
                                                                                                              removing the seed layer to form wiring arrower second insulating remained in the nattern arrower of conductors remained in the nattern arrower.
                                                                                              seed layer as a power supply layer; and
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                                                                                                                                                                                  tous remarked the forth in claim 1, wherein a forth in claim 1, wherein a A method as set forth in claim 1, wherein a
                                                                                                                    second insulating layer to the pattern groves.

of conductors remained in the pattern groves.
                                                                                                                               A method as set torth in claim i, wherein a set torth in claim is wherein as the different metal layers are filled with a plurality of different metal arounce are filled with a plurality when the nattern arounce are filled with a plurality when the nattern arounce are filled with a plurality when the nattern arounce are filled with a plurality when the nattern arounce are filled with a plurality when the nattern arounce are filled with a plurality when the nattern arounce are filled with a plurality wherein a set torth in claim is where the plurality of different metal layers are filled with a plurality where a plurality where a plurality where a plurality where are filled with
                                                                                                                                     Plurality of different metal layers are filled with the conductor, when the electrolytic plating.
                                                    15
                                                                                                                                                                                                       by the electrolytic plating. 2, wherein the A method as set forth in claim 2, wherein the
                                                                                                                                                     A method as set torth in claim it least two as of different metal layers are at least and a plurality of different metal anner have lawer and a
                                                                                                                                           conductor by the electrolytic plating.
                                                                                                                                                           plurality or different metal layers are at least two and a copper base layer and a metal layers consisting of a copper base layer and a metal layers are at least two and a
                                                                                                                                                                                                                             A method as set forth in claim 1, wherein the
                                                                              20
                                                                                                                                                                             A method as set forth in claim 1, wherein the a method as set forth in claim 1, wherein the first insulating layer is composed of a photosensitive first insulating resin:
                                                                                                                                                                                                                                                                              after the first insulating layer is light after
                                                                                                                                                                                             after the first insulating through which a after the form an opening, the substrate is to be exposed and developed to formed on the substrate is to be first wiring partern formed on the substrate is to be
                                                                                                                                                                    nickel barrier layer.
                                                                                                                                                                                                    exposed and developed to form an opening, through which be substrate is to be form an opening, through which the substrate is to be substrate and developed to formed on the substrate is to be first willing pattern formed to a second wiring nattern to be substrated and developed to form an opening, through which be the substrate is to be substrated in the substrate is to be substrated in the substrate is to be substrated in the substrated in
                                                                                                           25
                                                                                                                                                                                                         first wiring pattern formed on the substrate is to be second wiring pattern to be electrically connected to a second viring pattern the first electrically connected inculation laver the first electrically first inculation
                                                                                                                                                                                                               electrically connected to a second wifing patceri the first insulating layer, the first formed on the first insulating layer,
                                                                                                                                                                                      insulating resin:
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insulating layer is heated and hardened.

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5. A method as set forth in claim 1, wherein a semiconductor wafer is used as the substrate, the semiconductor wafer has an electrode terminal forming surface, on which the first insulating layer and the second insulating layer are formed, and the wiring pattern, which is electrically connected with electrode terminals of the semiconductor wafer, is formed.